

# NLSX4014

## 4-Bit 100 Mb/s Configurable Dual-Supply Level Translator

The NLSX4014 is a 4-bit configurable dual-supply bidirectional level translator without a direction control pin. The I/O  $V_{CC}$  and I/O  $V_L$  ports are designed to track two different power supply rails,  $V_{CC}$  and  $V_L$  respectively. The  $V_{CC}$  supply rail is configurable from 1.3 V to 4.5 V while the  $V_L$  supply rail is configurable from 0.9 V to ( $V_{CC} - 0.4$ ) V. This allows lower voltage logic signals on the  $V_L$  side to be translated into higher voltage logic signals on the  $V_{CC}$  side, and vice-versa. Both I/O ports are auto-sensing; thus, no direction pin is required.

The Output Enable (EN) input, when Low, disables both I/O ports by putting them in 3-state. This significantly reduces the supply currents from both  $V_{CC}$  and  $V_L$ . The EN signal is designed to track  $V_L$ .

### Features

- Wide High-Side  $V_{CC}$  Operating Range: 1.3 V to 4.5 V  
Wide Low-Side  $V_L$  Operating Range: 0.9 V to ( $V_{CC} - 0.4$ ) V
- Power Supply Isolation
  - ♦ All Outputs are in the High Impedance State if Either  $V_L$  or  $V_{CC}$  is at Ground
- High-Speed with 100 Mb/s Guaranteed Data Rate for  $V_L > 1.6$  V
- Low Bit-to-Bit Skew
- Overvoltage Tolerant Enable and I/O Pins
- Non-preferential Powerup Sequencing
- Small packaging: 1.7 mm x 2.0 mm UQFN12
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These are Pb-Free Devices

### Typical Applications

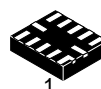
- Mobile Phones, PDAs, Other Portable Devices



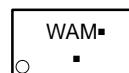
ON Semiconductor®

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### MARKING DIAGRAMS

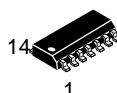


UQFN12  
MU SUFFIX  
CASE 523AE

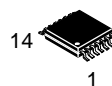
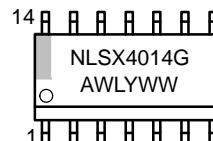


WA = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

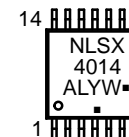
(Note: Microdot may be in either location)



SOIC-14  
D SUFFIX  
CASE 751A



TSSOP-14  
DT SUFFIX  
CASE 948G



A = Assembly Location  
L, WL = Wafer Lot  
Y, YY = Year  
W, WW = Work Week  
G or ▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping†
NLSX4014MUTAG	UQFN12 (Pb-Free)	3000/Tape & Reel
NLVSX4014MUTAG	UQFN12 (Pb-Free)	3000/Tape & Reel
NLSX4014DR2G	SO-14 (Pb-Free)	2500/Tape & Reel
NLSX4014DTR2G	TSSOP14 (Pb-Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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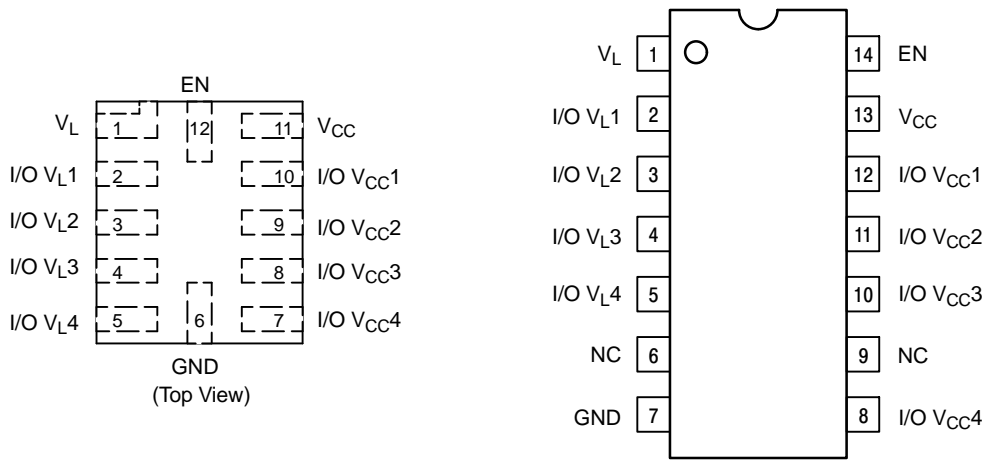


Figure 1. Pin Assignments

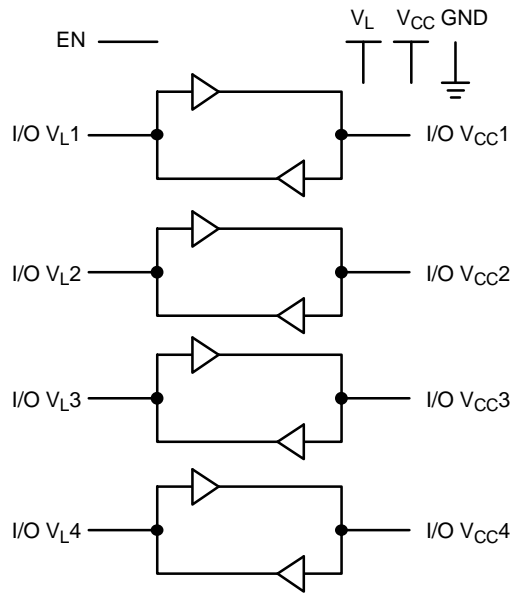


Figure 2. Logic Diagram

## PIN ASSIGNMENT

Pins	Description
V <sub>CC</sub>	V <sub>CC</sub> Input Voltage
V <sub>L</sub>	V <sub>L</sub> Input Voltage
GND	Ground
EN	Output Enable
I/O V <sub>CCn</sub>	I/O Port, Referenced to V <sub>CC</sub>
I/O V <sub>Ln</sub>	I/O Port, Referenced to V <sub>L</sub>

## FUNCTION TABLE

EN	Operating Mode
L	Hi-Z
H	I/O Buses Connected

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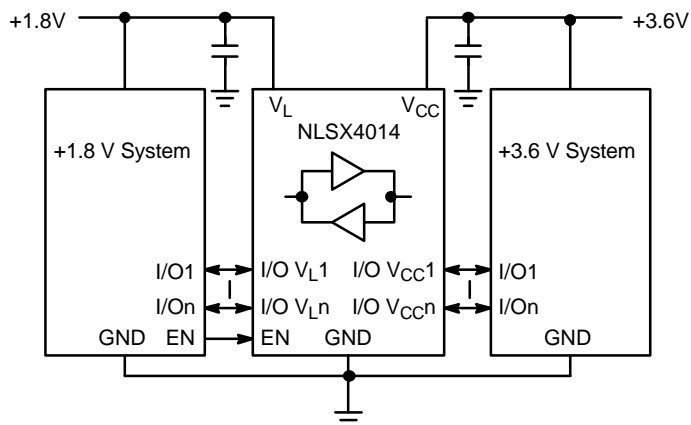


Figure 3. Typical Application Circuit

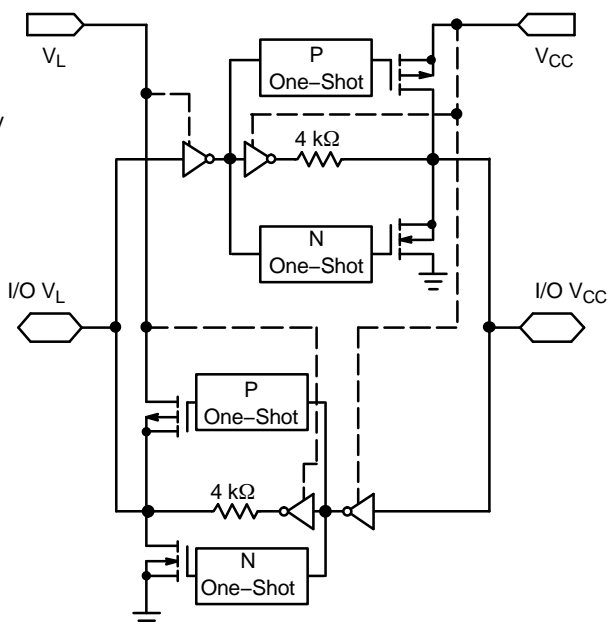


Figure 4. Simplified Functional Diagram (1 I/O Line)  
(EN = 1)

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## MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
$V_{CC}$	$V_{CC}$ Supply Voltage	-0.5 to +5.5		V
$V_L$	$V_L$ Supply Voltage	-0.5 to +5.5		V
I/O $V_{CC}$	$V_{CC}$ -Referenced DC Input/Output Voltage	-0.5 to ( $V_{CC} + 0.3$ )		V
I/O $V_L$	$V_L$ -Referenced DC Input/Output Voltage	-0.5 to ( $V_L + 0.3$ )		V
$V_{EN}$	Enable Control Pin DC Input Voltage	-0.5 to +5.5		V
$I_{IK}$	Input Diode Clamp Current	-50	$V_I < GND$	mA
$I_{OK}$	Output Diode Clamp Current	-50	$V_O < GND$	mA
$I_{CC}$	DC Supply Current Through $V_{CC}$	$\pm 100$		mA
$I_L$	DC Supply Current Through $V_L$	$\pm 100$		mA
$I_{GND}$	DC Ground Current Through Ground Pin	$\pm 100$		mA
$T_{STG}$	Storage Temperature	-65 to +150		$^{\circ}C$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	$V_{CC}$ Supply Voltage	1.3	4.5	V
$V_L$	$V_L$ Supply Voltage	0.9	$V_{CC} - 0.4$	V
$V_{EN}$	Enable Control Pin Voltage	GND	4.5	V
$V_{IO}$	Bus Input/Output Voltage	I/O $V_{CC}$ I/O $V_L$	GND 4.5	V
$T_A$	Operating Temperature Range	-40	+85	$^{\circ}C$
$\Delta I/\Delta V$	Input Transition Rise or Rate $V_I, V_{IO}$ from 30% to 70% of $V_{CC}$ ; $V_{CC} = 3.3 V \pm 0.3 V$	0	10	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

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## DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions (Note 1)	V <sub>CC</sub> (V) (Note 2)	V <sub>L</sub> (V) (Note 3)	-40°C to +85°C			Unit
					Min	Typ (Note 4)	Max	
V <sub>IHC</sub>	I/O V <sub>CC</sub> Input HIGH Voltage		1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	0.8 * V <sub>CC</sub>	-	-	V
V <sub>ILC</sub>	I/O V <sub>CC</sub> Input LOW Voltage		1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	-	-	0.2 * V <sub>CC</sub>	V
V <sub>IHL</sub>	I/O V <sub>L</sub> Input HIGH Voltage		1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	0.8 * V <sub>L</sub>	-	-	V
V <sub>ILL</sub>	I/O V <sub>L</sub> Input LOW Voltage		1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	-	-	0.2 * V <sub>L</sub>	V
V <sub>IH</sub>	Control Pin Input HIGH Voltage	T <sub>A</sub> = +25°C	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	0.8 * V <sub>L</sub>	-	-	V
V <sub>IL</sub>	Control Pin Input LOW Voltage	T <sub>A</sub> = +25°C	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	-	-	0.2 * V <sub>L</sub>	V
V <sub>OHC</sub>	I/O V <sub>CC</sub> Output HIGH Voltage	I/O V <sub>CC</sub> Source Current = 20 μA	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	0.8 * V <sub>CC</sub>	-	-	V
V <sub>OLC</sub>	I/O V <sub>CC</sub> Output LOW Voltage	I/O V <sub>CC</sub> Sink Current = 20 μA	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	-	-	0.2 * V <sub>CC</sub>	V
V <sub>OHL</sub>	I/O V <sub>L</sub> Output HIGH Voltage	I/O V <sub>L</sub> Source Current = 20 μA	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	0.8 * V <sub>L</sub>	-	-	V
V <sub>OLL</sub>	I/O V <sub>L</sub> Output LOW Voltage	I/O V <sub>L</sub> Sink Current = 20 μA	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	-	-	0.2 * V <sub>L</sub>	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Normal test conditions are V<sub>EN</sub> = 0 V, C<sub>IOVCC</sub> = 15 pF and C<sub>IOVL</sub> = 15 pF, unless otherwise specified.
2. V<sub>CC</sub> is the supply voltage associated with the high voltage port, and V<sub>CC</sub> ranges from +1.3 V to 4.5 V under normal operating conditions.
3. V<sub>L</sub> is the supply voltage associated with the low voltage port. V<sub>L</sub> must be less than or equal to (V<sub>CC</sub> - 0.4) V during normal operation. However, during startup and shutdown conditions, V<sub>L</sub> can be greater than (V<sub>CC</sub> - 0.4) V.
4. Typical values are for V<sub>CC</sub> = +2.8 V, V<sub>L</sub> = +1.8 V and T<sub>A</sub> = +25°C. All units are production tested at T<sub>A</sub> = +25°C. Limits over the operating temperature range are guaranteed by design.

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## POWER CONSUMPTION

Symbol	Parameter	Test Conditions (Note 5)	V <sub>CC</sub> (V) (Note 6)	V <sub>L</sub> (V) (Note 7)	-40°C to +85°C			Unit
					Min	Typ	Max	
I <sub>Q-VCC</sub>	Supply Current from V <sub>CC</sub>	EN = V <sub>L</sub> ; I/O V <sub>CCn</sub> = 0 V, I/O V <sub>Ln</sub> = 0 V, I/O V <sub>CCn</sub> = V <sub>CC</sub> or I/O V <sub>Ln</sub> = V <sub>L</sub> and I <sub>o</sub> = 0	1.3 to 3.6	0.9 to (V <sub>CC</sub> - 0.4)	-	-	1.0	μA
			0	4.1	-	-	2.0	
			4.5	0	-	-	2.0	
I <sub>Q-VL</sub>	Supply Current from V <sub>L</sub>	EN = V <sub>L</sub> ; I/O V <sub>CCn</sub> = 0 V, I/O V <sub>Ln</sub> = 0 V, I/O V <sub>CCn</sub> = V <sub>CC</sub> or I/O V <sub>Ln</sub> = V <sub>L</sub> and I <sub>o</sub> = 0	1.3 to 3.6	0.9 to (V <sub>CC</sub> - 0.4)	-	-	1.0	μA
				< (V <sub>CC</sub> - 0.2)				
			0	4.1	-	-	2.0	
		EN = V <sub>L</sub> ; I/O V <sub>CCn</sub> = 0 V, I/O V <sub>Ln</sub> = 0 V, I/O V <sub>CCn</sub> = V <sub>CC</sub> or I/O V <sub>Ln</sub> = (V <sub>CC</sub> - 0.2 V) and I <sub>o</sub> = 0	4.5	0				
I <sub>TS-VCC</sub>	V <sub>CC</sub> Tristate Output Mode Supply Current	EN = 0 V	1.3 to 3.6	0.9 to (V <sub>CC</sub> - 0.4)	-	-	1.0	μA
I <sub>TS-VL</sub>	V <sub>L</sub> Tristate Output Mode Supply Current	EN = 0 V	1.3 to 3.6	0.9 to (V <sub>CC</sub> - 0.4)	-	-	0.2	μA
		EN = 0 V		V <sub>CC</sub> - 0.2	-	-	2.0	
I <sub>OZ</sub>	I/O Tristate Output Mode Leakage Current	EN = 0 V	1.3 to 3.6	0.9 to (V <sub>CC</sub> - 0.4)	-	-	0.15	μA
		EN = 0 V		V <sub>CC</sub> - 0.2	-	-	2.0	
I <sub>EN</sub>	Output Enable Pin Input Current	-	1.3 to 3.6	0.9 to (V <sub>CC</sub> - 0.4)	-	-	1.0	μA
I <sub>OFF</sub>	V <sub>L</sub> Port	I/O V <sub>Ln</sub> = 0 to 4.1 V	0 to 4.5	0	-	-	2.0	μA
	V <sub>CC</sub> Port	I/O V <sub>CCn</sub> = 0 to 4.5 V	0	0 to 4.1	-	-	2.0	

5. Normal test conditions are V<sub>EN</sub> = 0 V, C<sub>I<sub>O</sub>V<sub>CC</sub></sub> = 15 pF and C<sub>I<sub>O</sub>V<sub>L</sub></sub> = 15 pF, unless otherwise specified.

6. V<sub>CC</sub> is the supply voltage associated with the high voltage port, and V<sub>CC</sub> ranges from +1.3 V to 3.6 V.

7. V<sub>L</sub> is the supply voltage associated with the low voltage port. V<sub>L</sub> must be less than or equal to (V<sub>CC</sub> - 0.4) V during normal operation. However, during startup and shutdown conditions, V<sub>L</sub> can be greater than (V<sub>CC</sub> - 0.4) V.

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## TIMING CHARACTERISTICS

Symbol	Parameter	Test Conditions (Note 8)	V <sub>CC</sub> (V) (Note 9)	V <sub>L</sub> (V) (Note 10)	-40°C to +85°C			Unit
					Min	Typ (Note 11)	Max	
t <sub>R-VCC</sub>	I/O V <sub>CC</sub> Rise Time (Output = I/O_V <sub>CC</sub> )	C <sub>IOVCC</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		0.7	2.4	ns
t <sub>F-VCC</sub>	I/O V <sub>CC</sub> Falltime (Output = I/O_V <sub>CC</sub> )	C <sub>IOVCC</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		0.5	1.0	ns
t <sub>R-VL</sub>	I/O V <sub>L</sub> Risetime (Output = I/O_V <sub>L</sub> )	C <sub>IOVL</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		1.0	3.8	ns
t <sub>F-VL</sub>	I/O V <sub>L</sub> Falltime (Output = I/O_V <sub>L</sub> )	C <sub>IOVL</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		0.6	1.2	ns
Z <sub>O-VCC</sub>	I/O V <sub>CC</sub> One-Shot Output Impedance		1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		30		Ω
Z <sub>O-VL</sub>	I/O V <sub>L</sub> One-Shot Output Impedance		1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		30		Ω
t <sub>PD_VL-VCC</sub>	Propagation Delay (Output = I/O_V <sub>CC</sub> , t <sub>PHL</sub> , t <sub>PLH</sub> )	C <sub>IOVCC</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		4.5	9.3	ns
t <sub>PD_VCC-VL</sub>	Propagation Delay (Output = I/O_V <sub>L</sub> , t <sub>PHL</sub> , t <sub>PLH</sub> )	C <sub>IOVL</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		3.0	6.5	ns
t <sub>SK_VL-VCC</sub>	Channel-to-Channel Skew (Output = I/O_V <sub>CC</sub> )	C <sub>IOVCC</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		0.2	0.3	nS
t <sub>SK_VCC-VL</sub>	Channel-to-Channel Skew (Output = I/O_V <sub>L</sub> )	C <sub>IOVCC</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		0.2	0.3	nS
MDR	Maximum Data Rate	(Output = I/O_V <sub>CC</sub> , C <sub>IOVCC</sub> = 15 pF) (Output = I/O_V <sub>L</sub> , C <sub>IOVL</sub> = 15 pF)	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)	110			Mb/s
			> 2.2	> 1.8	140			

8. Normal test conditions are V<sub>EN</sub> = 0 V, C<sub>IOVCC</sub> = 15 pF and C<sub>IOVL</sub> = 15 pF, unless otherwise specified.

9. V<sub>CC</sub> is the supply voltage associated with the high voltage port, and V<sub>CC</sub> ranges from +1.3 V to 4.5 V under normal operating conditions.

10. V<sub>L</sub> is the supply voltage associated with the low voltage port. V<sub>L</sub> must be less than or equal to (V<sub>CC</sub> - 0.4) V during normal operation. However, during startup and shutdown conditions, V<sub>L</sub> can be greater than (V<sub>CC</sub> - 0.4) V.

11. Typical values are for V<sub>CC</sub> = +2.8 V, V<sub>L</sub> = +1.8 V and T<sub>A</sub> = +25°C. All units are production tested at T<sub>A</sub> = +25°C. Limits over the operating temperature range are guaranteed by design.

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## ENABLE / DISABLE TIME MEASUREMENTS

Symbol	Parameter	Test Conditions (Note 12)	V <sub>CC</sub> (V) (Note 13)	V <sub>L</sub> (V) (Note 14)	-40°C to +85°C			Unit
					Min	Typ (Note 15)	Max	
t <sub>EN-VCC</sub>	Turn-On Enable Time (Output = I/O_V <sub>CC</sub> , t <sub>pZH</sub> )	C <sub>IOVCC</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		130	180	ns
	Turn-On Enable Time (Output = I/O_V <sub>CC</sub> , t <sub>pZL</sub> )	C <sub>IOVL</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		100	150	ns
t <sub>EN-VL</sub>	Turn-On Enable Time (Output = I/O_V <sub>L</sub> , t <sub>pZH</sub> )	C <sub>IOVCC</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		95	185	ns
	Turn-On Enable Time (Output = I/O_V <sub>L</sub> , t <sub>pZL</sub> )	C <sub>IOVL</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		70	110	ns
t <sub>DIS-VCC</sub>	Turn-Off Disable Time (Output = I/O_V <sub>CC</sub> , t <sub>pHZ</sub> )	C <sub>IOVCC</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		175	250	ns
	Propagation Delay (Output = I/O_V <sub>CC</sub> , t <sub>pLZ</sub> )	C <sub>IOVL</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		150	190	ns
t <sub>DIS-VL</sub>	Turn-Off Disable Time (Output = I/O_V <sub>L</sub> , t <sub>pHZ</sub> )	C <sub>IOVCC</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		180	250	ns
	Propagation Delay (Output = I/O_V <sub>L</sub> , t <sub>pLZ</sub> )	C <sub>IOVL</sub> = 15 pF	1.3 to 4.5	0.9 to (V <sub>CC</sub> - 0.4)		160	220	ns

12. Normal test conditions are V<sub>EN</sub> = 0 V, C<sub>IOVCC</sub> = 15 pF and C<sub>IOVL</sub> = 15 pF, unless otherwise specified.

13. V<sub>CC</sub> is the supply voltage associated with the high voltage port, and V<sub>CC</sub> ranges from +1.3 V to 4.5 V under normal operating conditions.

14. V<sub>L</sub> is the supply voltage associated with the low voltage port. V<sub>L</sub> must be less than or equal to (V<sub>CC</sub> - 0.4) V during normal operation. However, during startup and shutdown conditions, V<sub>L</sub> can be greater than (V<sub>CC</sub> - 0.4) V.

15. Typical values are for V<sub>CC</sub> = +2.8 V, V<sub>L</sub> = +1.8 V and T<sub>A</sub> = +25 °C. All units are production tested at T<sub>A</sub> = +25 °C. Limits over the operating temperature range are guaranteed by design.

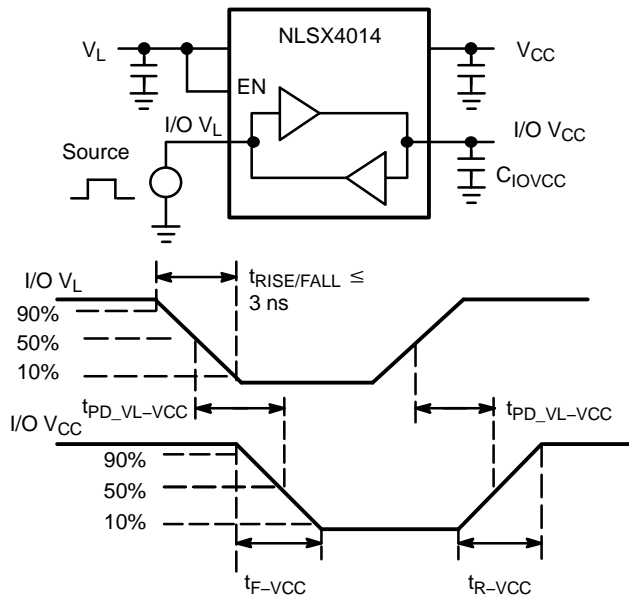


Figure 5. Driving I/O V<sub>L</sub> Test Circuit and Timing

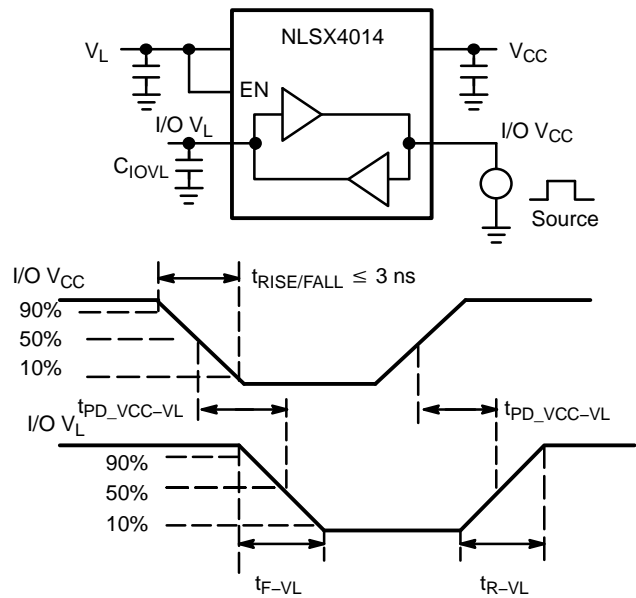
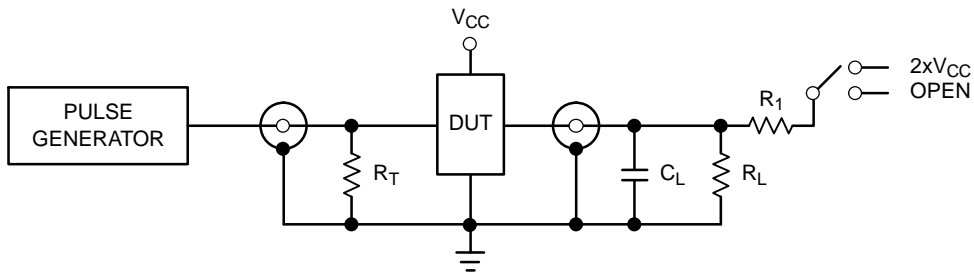


Figure 6. Driving I/O V<sub>CC</sub> Test Circuit and Timing



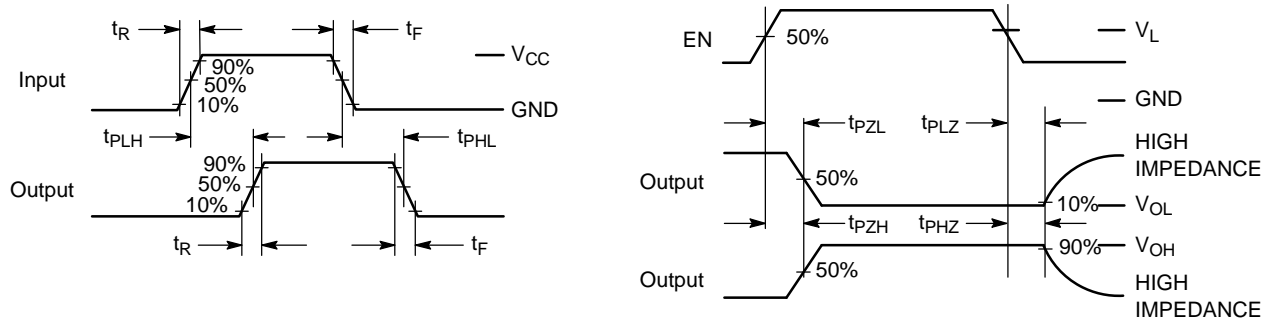
# NLSX4014



Test	Switch
$t_{PZH}$ , $t_{PHZ}$	Open
$t_{PZL}$ , $t_{PLZ}$	$2 \times V_{CC}$

$C_L = 15 \text{ pF}$  or equivalent (Includes jig and probe capacitance)  
 $R_L = R_1 = 50 \text{ k}\Omega$  or equivalent  
 $R_T = Z_{OUT}$  of pulse generator (typically  $50 \Omega$ )

**Figure 7. Test Circuit for Enable/Disable Time Measurement**



**Figure 8. Timing Definitions for Propagation Delays and Enable/Disable Measurement**

## IMPORTANT APPLICATIONS INFORMATION

### Level Translator Architecture

The NLSX4014 auto sense translator provides bi-directional voltage level shifting to transfer data in multiple supply voltage systems. This device has two supply voltages,  $V_L$  and  $V_{CC}$ , which set the logic levels on the input and output sides of the translator. When used to transfer data from the  $V_L$  to the  $V_{CC}$  ports, input signals referenced to the  $V_L$  supply are translated to output signals with a logic level matched to  $V_{CC}$ . In a similar manner, the  $V_{CC}$  to  $V_L$  translation shifts input signals with a logic level compatible to  $V_{CC}$  to an output signal matched to  $V_L$ .

The NLSX4014 consists of four bi-directional channels that independently determine the direction of the data flow without requiring a directional pin. The one-shot circuits are used to detect the rising or falling input signals. In addition, the one shots decrease the rise and fall time of the output signal for high-to-low and low-to-high transitions.

### Input Driver Requirements

For proper operation, the input driver to the auto sense translator should be capable of driving 2.0 mA of peak output current.

### Output Load Requirements

The NLSX4014 is designed to drive CMOS inputs. Resistive pullup or pulldown loads of less than 50 k $\Omega$  should not be used with this device. The NLSX3373 or NLSX3378 open-drain auto sense translators are alternate translator options for an application such as the I<sup>2</sup>C bus that requires pullup resistors.

### Enable Input (EN)

The NLSX4014 has an Enable pin (EN) that provides tri-state operation at the I/O pins. Driving the Enable pin to a low logic level minimizes the power consumption of the device and drives the I/O  $V_{CC}$  and I/O  $V_L$  pins to a high impedance state. Normal translation operation occurs when the EN pin is equal to a logic high signal. The EN pin is referenced to the  $V_L$  supply and has Over-Voltage Tolerant (OVT) protection.

### Uni-Directional versus Bi-Directional Translation

The NLSX4014 can function as a non-inverting uni-directional translator. One advantage of using the translator as a uni-directional device is that each I/O pin can be configured as either an input or output. The configurable input or output feature is especially useful in applications such as SPI that use multiple uni-directional I/O lines to send data to and from a device. The flexible I/O port of the auto sense translator simplifies the trace connections on the PCB.

### Power Supply Guidelines

It is recommended that the  $V_L$  supply should be less than or equal to the value of the  $V_{CC}$  minus 0.4 V. The sequencing of the power supplies will not damage the device during the power up operation; however, the current consumption of the device will increase if  $V_L$  exceeds  $V_{CC}$  minus 0.4 V. In addition, the I/O  $V_{CC}$  and I/O  $V_L$  pins are in the high impedance state if either supply voltage is equal to 0 V.

For optimal performance, 0.01 to 0.1  $\mu$ F decoupling capacitors should be used on the  $V_L$  and  $V_{CC}$  power supply pins. Ceramic capacitors are a good design choice to filter and bypass any noise signals on the power supply voltage lines to the ground plane of the PCB. The noise immunity will be maximized by placing the capacitors as close as possible to the supply and ground pins, along with minimizing the PCB connection traces.

The NLSX4014 provides power supply isolation if either supply voltage  $V_L$  or  $V_{CC}$  is equal to 0 V. The isolation occurs because the I/O pins are in the high impedance state. It is recommended that pulldown resistors should be used if the  $V_L$  or  $V_{CC}$  are floated or in a high impedance state. A pulldown resistor connected from the supply voltage to ground ensures that the translator's supply voltage is equal to 0 V.

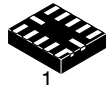
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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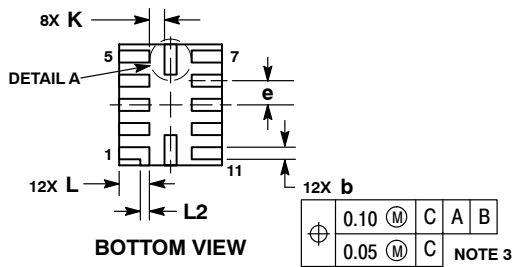
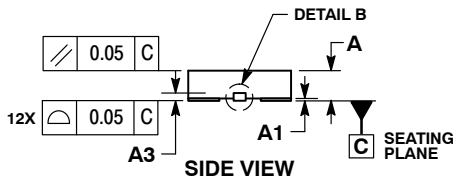
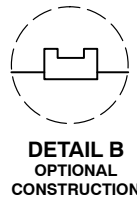
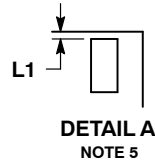
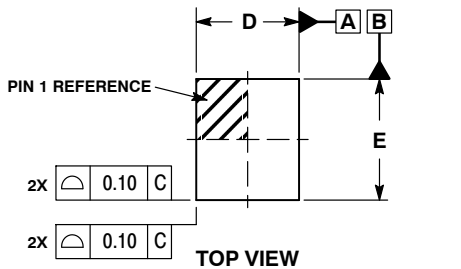


## UQFN12 1.7x2.0, 0.4P CASE 523AE-01 ISSUE A

DATE 11 JUN 2007



SCALE 4:1

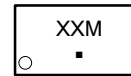


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
- MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH 0.03 MAX ON BOTTOM SURFACE OF TERMINALS.
- DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
D	1.70 BSC	
E	2.00 BSC	
e	0.40 BSC	
K	0.20	---
L	0.45	0.55
L1	0.00	0.03
L2	0.15 REF	

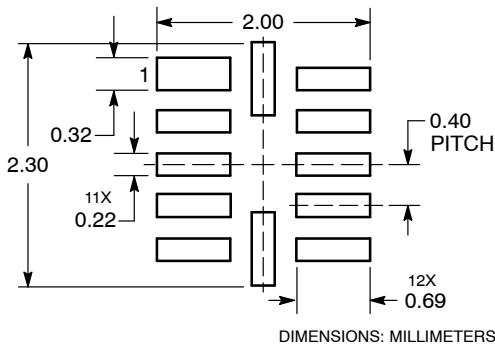
### GENERIC MARKING DIAGRAM\*



- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

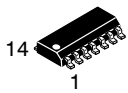
### MOUNTING FOOTPRINT SOLDERMASK DEFINED



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DESCRIPTION:	UQFN12 1.7 X 2.0, 0.4P	PAGE 1 OF 1

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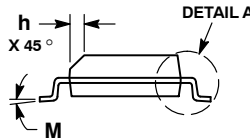
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-14 NB  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM\*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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**SOIC-14**  
**CASE 751A-03**  
**ISSUE L**

DATE 03 FEB 2016

STYLE 1:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. NO CONNECTION  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 2:  
 CANCELLED

STYLE 3:  
 PIN 1. NO CONNECTION  
 2. ANODE  
 3. ANODE  
 4. NO CONNECTION  
 5. ANODE  
 6. NO CONNECTION  
 7. ANODE  
 8. ANODE  
 9. ANODE  
 10. NO CONNECTION  
 11. ANODE  
 12. ANODE  
 13. NO CONNECTION  
 14. COMMON CATHODE

STYLE 4:  
 PIN 1. NO CONNECTION  
 2. CATHODE  
 3. CATHODE  
 4. NO CONNECTION  
 5. CATHODE  
 6. NO CONNECTION  
 7. CATHODE  
 8. CATHODE  
 9. CATHODE  
 10. NO CONNECTION  
 11. CATHODE  
 12. CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 5:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. COMMON ANODE  
 8. COMMON CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 6:  
 PIN 1. CATHODE  
 2. CATHODE  
 3. CATHODE  
 4. CATHODE  
 5. CATHODE  
 6. CATHODE  
 7. CATHODE  
 8. ANODE  
 9. ANODE  
 10. ANODE  
 11. ANODE  
 12. ANODE  
 13. ANODE  
 14. ANODE

STYLE 7:  
 PIN 1. ANODE/CATHODE  
 2. COMMON ANODE  
 3. COMMON CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. COMMON CATHODE  
 12. COMMON ANODE  
 13. ANODE/CATHODE  
 14. ANODE/CATHODE

STYLE 8:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. COMMON ANODE  
 8. COMMON ANODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. NO CONNECTION  
 12. ANODE/CATHODE  
 13. ANODE/CATHODE  
 14. COMMON CATHODE

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



**TSSOP-14 WB**  
CASE 948G  
ISSUE C

DATE 17 FEB 2016

SCALE 2:1



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**GENERIC MARKING DIAGRAM\***

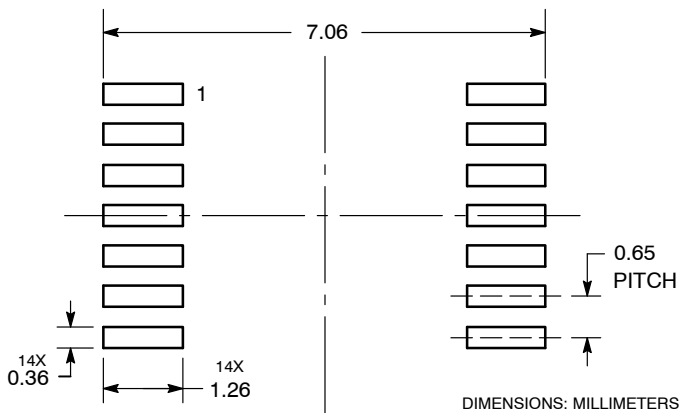


- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

**SOLDERING FOOTPRINT**



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<b>DESCRIPTION:</b>	<b>TSSOP-14 WB</b>	<b>PAGE 1 OF 1</b>

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